

# BLS170IRC-2A

2.00mm x 1.25mm x 1.10mm (0805) SMD Infrared LED

Surface Mount Chip LED

Technical Data Sheet

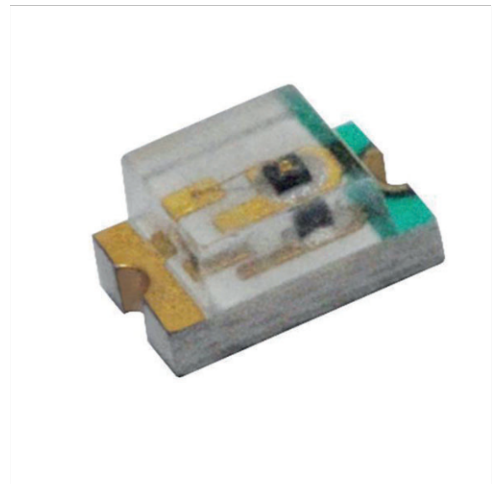


## Features:

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- The product itself will remain within RoHS compliant versi

## Applications:

- B mounted infrared sensor.
- Infrared emitting for miniature light barrier.
- Floppy disk drive.
- Optoelectronic switch.



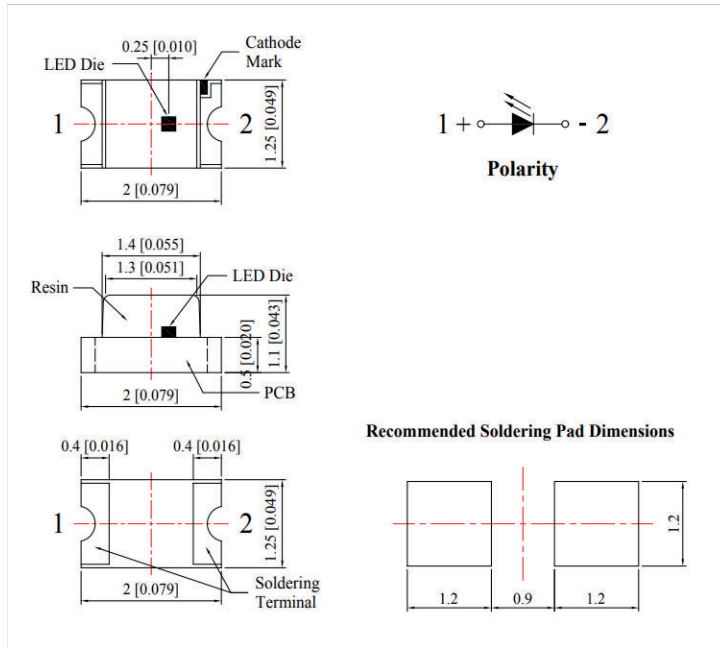
## Descriptions:

- The S170IR is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with flat top view lens.
- The device is spectrally matched with photodiode and phototrans

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Part No.	Emitting Color	Lens Color
BLS170IRC-2A	Infrared	Water Clear

## Package Dimensions:



## Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25$  mm (.010") unless otherwise noted.
3. Protruded resin under flange is 1.00mm (.039") max.

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## Absolute Maximum Ratings at Ta=25°C

Parameters	Symbol	Max	Unit
Power Dissipation	Pd	90	mW
Peak Forward Current <sup>(a)</sup>	IFP	1	mA
DC Forward Current <sup>(b)</sup>	IF	50	mA
Reverse Voltage	VR	5	V
Operating Temperature Range	Topr	-40°C to +80°C	
Storage Temperature Range	Tstg	-40°C to +85°C	
Soldering Temperature	Tsld	260°C for 5 seconds	

Notes:

a. Derate linearly as shown in derating curve.

b. Duty Factor = 10%, Frequency = 1 kHz

## Electrical Optical Characteristics at Ta=25°C

Parameters	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Radiant Intensity	Ee	0.2	0.35	---	mW/sr	IF=20mA
		---	2.5	---		IF=100mA (Pulse Width≤100μs, Duty≤1%)
Viewing Angle <sup>(b)</sup>	2θ1/2	---	140	---	deg.	IF=20mA
Peak Emission Wavelength	λp	---	940	---	nm	IF=20mA
Spectral Line Half-Width	Δλ	---	50	---	nm	IF=20mA
Forward Voltage	VF	0.8	1.2	1.5	V	IF=20mA
		---	1.6	1.8		IF=100mA (Pulse Width≤100μs, Duty≤1%)
Reverse Current	IR	---	---	10	μA	VR=5V

### Notes:

a. 2θ1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.

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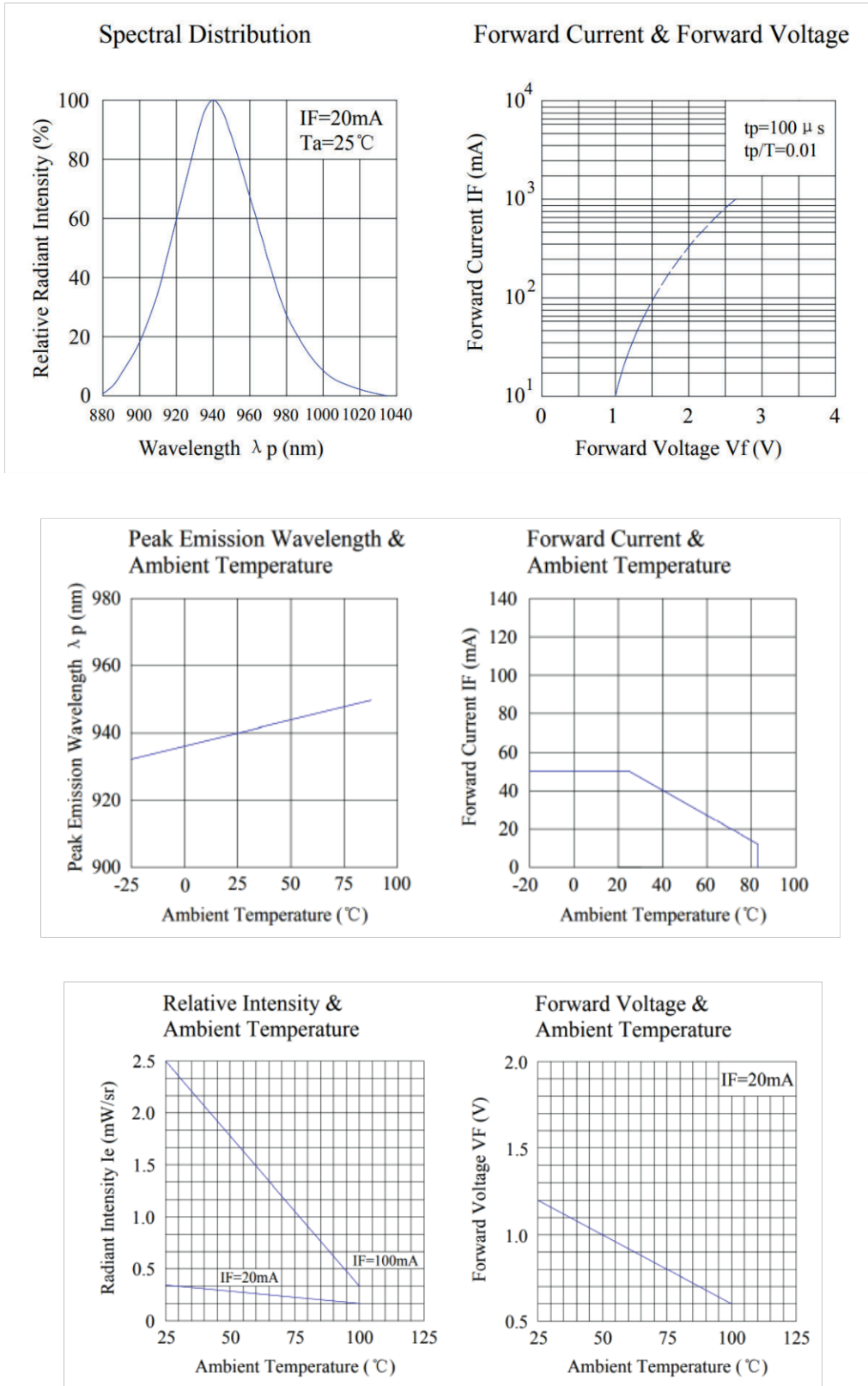
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## Typical Electrical / Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)



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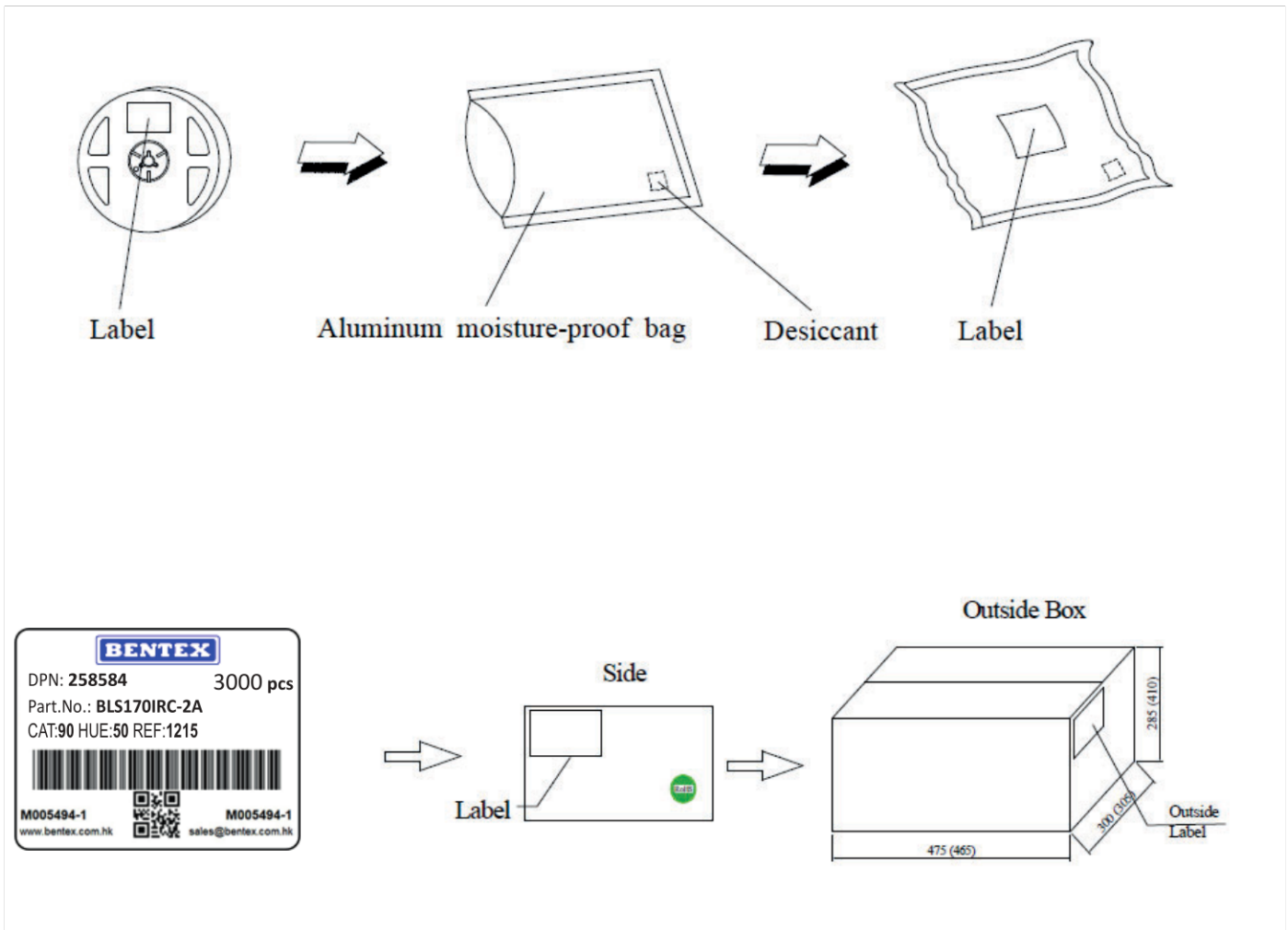
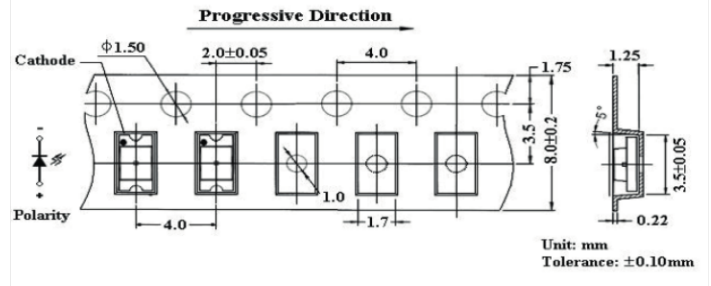
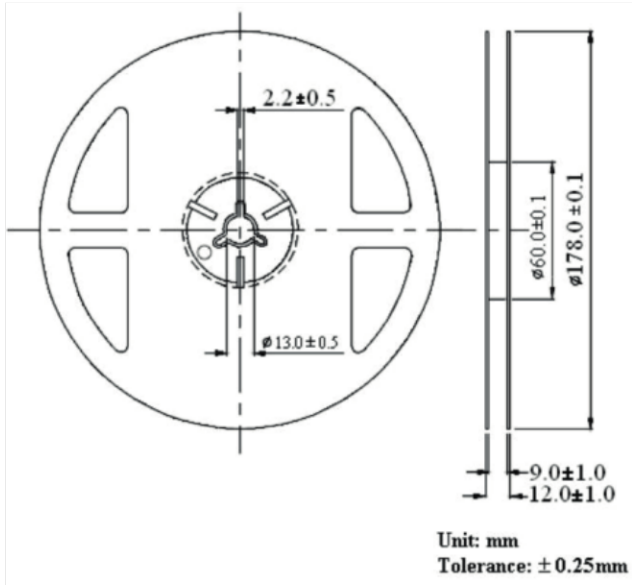
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## Reel and Carrier Tape Dimensions:

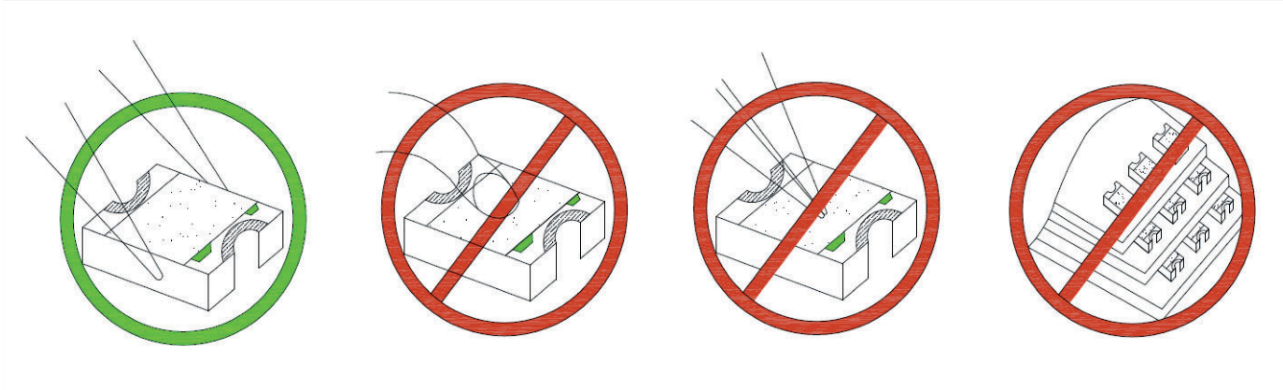
Loaded quantity 3000 pcs per reel.



## CAUTIONS

### 1. Handling Precautions:

- 1.1. Handle the component along the side surfaces by using forceps or appropriate tools.
- 1.2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.
- 1.3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



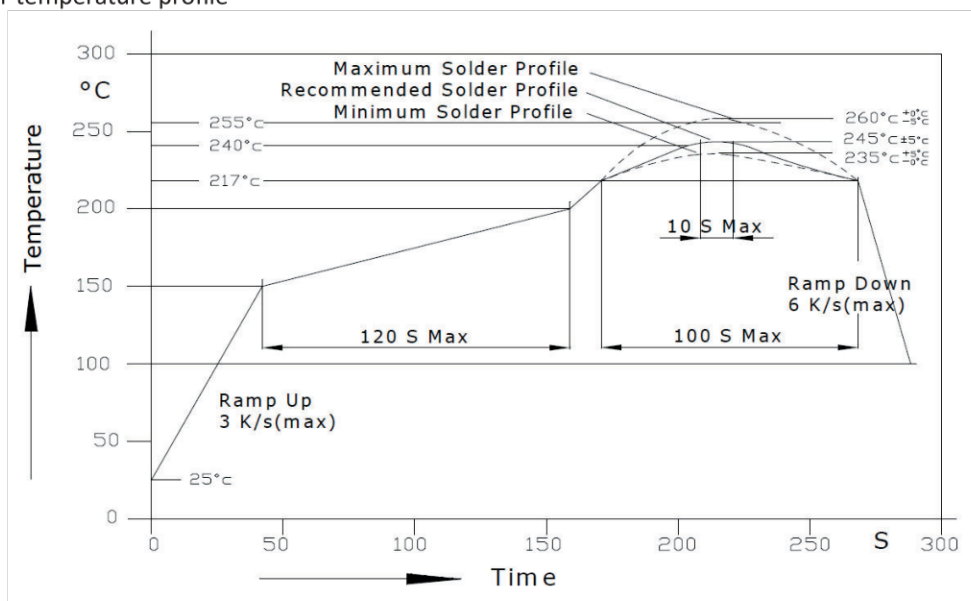
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

### 2. Storage

- 2.1. Do not open moisture proof bag before the products are ready to use.
- 2.2. Before opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.
- 2.3. The LEDs should be used within a year.
- 2.4. After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.
- 2.5. The LEDs should be used within 168 hours after opening the package.
- 2.6. If the moisture adsorbent material has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 65±5°C for 24 hours. Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LEDs if necessary.

### 3. Soldering Condition

#### 3.1. Pb-free solder temperature profile



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- 3.2. Reflow soldering should not be done more than two times.
- 3.3. When soldering, do not put stress on the LEDs during heating.
- 3.4. After soldering, do not warp the circuit board.
- 3.5. Recommended soldering conditions:

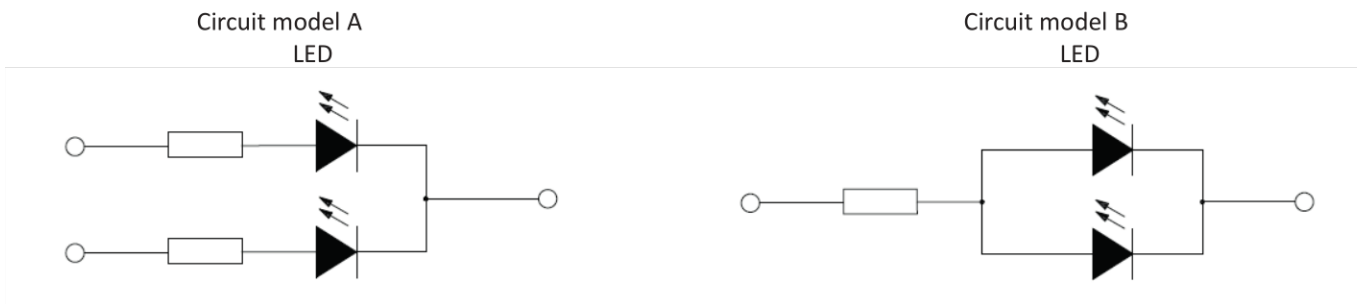
Soldering Iron		Reflow soldering	
Temperature	300°C Max.	Pre-heat	150-200°C Max.
		Pre-heat Time	120 sec. Max.
Soldering Time	3 sec. Max. (one time only)	Solder Wave	260°C Max.
		Soldering Time	10 sec. Max.(Max. two times)

3.6. Because different board designs use different number and types of devices, solder pastes, reflow ovens, and circuit boards, no single temperature profile works for all possible combinations. However, you can successfully mount your packages to the PCB by following the proper guidelines and PCB-specific characterization.

## 4. Drive Method

4.1. An LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.

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(A) Recommended circuit

(B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.

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